

Zheng Zhou

List of Publications by Year in descending order

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14
papers

104
citations

2258059

3
h-index

2053705

5
g-index

14
all docs

14
docs citations

14
times ranked

84
citing authors

#	ARTICLE	IF	CITATIONS
1	Fabrication of fully covered Cu@Ag core-shell nanoparticles by compound method and anti-oxidation performance. Nanotechnology, 2020, 31, 175601.	2.6	19
2	Microstructural and Micromechanical Characteristics of Tin-Based Solders Under Self-Propagating Exothermic Reaction Heating. Journal of Electronic Materials, 2020, 49, 6214-6222.	2.2	3
3	Preparation of Micro/nano Sized Al ₂ O ₃ Using the By-product of Al-based Composites Hydrolysis Reaction. IOP Conference Series: Earth and Environmental Science, 2020, 552, 012021.	0.3	0
4	Hydrogen generation from the reaction of Al-based composites activated by low-melting-point metals/oxides/salts with water. Energy, 2019, 188, 116107.	8.8	43
5	Effects of preparation method on the hydrolytic hydrogen production performance of Al-rich alloys. Journal of Alloys and Compounds, 2019, 796, 210-220.	5.5	35
6	Study of Fusion Thickness of Tin Solder Heating by Self-Propagating Exothermic Reaction. Journal of Electronic Materials, 2018, 47, 7435-7448.	2.2	1
7	Wettability and Shear Strength of SAC305 Based Composite Solder with co-doping X (Ni or Tj) ETQq1 1 0.784314 rgBT /Overlock 10		
8	Research on surface anti-reflection properties of nanowire array structure based on silicon solar cells. , 2017, , .		1
9	Study on the microstructure of Si/solder/Si joint based on Al/Ni self-propagating exothermic reaction. , 2017, , .		0
10	Comparison on microstructure and mechanical property of composite solder joints with different reinforcements. , 2017, , .		0
11	Solidification microstructure of tin-based solder in the rapid cooling condition. , 2017, , .		0
12	Mechanical property of Cu-Sn-Ni intermetallics in the full intermetallic micro-joints formed with transient liquid phase soldering. , 2017, , .		1
13	Simulation of the temperature field for bonding IGBT chip and DBC substrate using Al/Ni self-propagating foil. , 2017, , .		1
14	Si/Si bonding based on self-propagating exothermic reaction. , 2016, , .		0